

PIXAPP Advanced Photonic Packaging Training Programme

PIXAPP, the European Photonic Packaging Pilot Line, is proud to announce opening of its new hands-on training programme in advanced photonic packaging. The first training course was held at Tyndall National Institute, University College Cork in January, with participants from around the world attending the week-long course (see training programme video – www.pixapp.eu).

Photonic device packaging can account for over 50% of the photonic product manufacturing cost. Therefore, it is vital that industries developing photonic-based products have an understanding of the materials, technologies and processes required to package photonic devices. The PIXAPP training programme provides industry, and those involved in photonic product development, with the fundamental technical skills in package design, assembly and reliability testing. The course covers the key optical, electrical, thermal and mechanical aspects of packaging technologies. It also provides an overview of packaging equipment and photonic device foundry services, which are critical parts of the packaging ecosystem. Please contact with PIXAPP Gateway office at Tyndall National Institute for more information about the next course which is scheduled to summer 2018 (info@pixapp.eu). PIXAPP will also be attending OFC in San Diego (Booth 5420) and is sponsoring the OIDA workshop on ‘Scalable Integrated Photonics for 5G and the Internet of Things’ (San Diego Convention Centre, March 11th).

About the PIXAPP Pilot Line

PIXAPP is funded by the European Commission and was established in January 2017. The goal of PIXAPP is to support the transition of integrated photonic devices from prototypes to manufacture via pilot-scale production. PIXAPP is a distributed consortium of partners with a wide range of packaging technologies and capabilities, from the development of advanced photonic prototypes through to medium-volume commercial production. A key focus of PIXAPP is to establish a set of packaging design standards and related design rules which provides users with easy access to well-defined and qualified packaging technologies that are sufficiently flexible to address a wide range of markets, from communications to sensing and medical diagnostics. PIXAPP also provides advanced training to industry, including practical hands-on laboratory-based training using state-of-the-art equipment and training on advanced PIC design, test and reliability systems.

